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Patent

FEB 13 2006

Customer No.: 31561
Docket No. : 10544-US-PA
Application No.: 10/709,179

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Chang et al.
 Application No. : 10/709,179
 Filed : April 19, 2004
 For : STACK-TYPE MULTI-CHIP PACKAGE AND METHOD
 OF FABRICATING BUMPS ON THE BACKSIDE OF A
 CHIP
 Art Unit : 2814
 Examiner : HA, NATHAN W.

NOTICE OF APPEAL FROM THE EXAMINER TO THE BOARD OF PATENT
APPEALS AND INTERFERENCES

U.S. Patent and Trademark Office
 Commissioner for Patents
 Customer Window, Mail Stop **AF**
 Randolph Building, 401 Dulany Street
 Alexandria, VA 22314

Applicants hereby appeal to the Board of Patent Appeals and Interferences from
 the last decision of the examiner

The fee for this Notice of Appeal is (37 CFR 1.17(b)) \$500.00.
 1 month extension of time is requested. The time extension fee is
\$ 120.00.

Please charge the amount of \$620.00 to account No. 50-2620 (Order No.:
 10544-US-PA)

I am the

Applicant/inventor
 Assignee of record of the entire interest. Statement under 37 CFR
 3.73b is enclosed.
 Attorney or agent of record
 Attorney or agent acting under 37 CFR 1.34(a).
 Registration number if acting under 37 CFR 1.34(a)._____

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01 FC:1251 120.00 DA
02 FC:1401 500.00 DA

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Respectfully Submitted,
JIANQ CHYUN Intellectual Property Office

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